PA-307479

Product Advisory

Issue Date: 30-April-2026

Change Description:
Introduction of new backside metallization for internal SiPM die

Parts Affected:
AFBR-S4N44P164M
AFBR-S4N44P044M
AFBR-S4N22P014M
AFBR-S4N44P014M
AFBR-S4N66P014M
AFBR-S4N66P024M

Description and Extent of Change:
We have successfully qualified a new Silver (Ag)-based backside metallization for the internal SiPM die, which will be used in addition to the existing Gold (Au)-based metallization. Products will be supplied with either the Au-based or the newly qualified Ag-based backside metallization. The solder interface is not changed. This addition is designed to maintain our strict performance and reliability standards while establishing a more sustainable supply chain.

Current	New
Au-based SiPM die backside metallization	Au-based SiPM die backside metallization or Ag-based SiPM die backside metallization (no change of product appearance and solder-pads)

Reasons for Change:
Assurance of continuous and reliable product supply.

Effect of Change on Fit, Form, Function, Quality, or Reliability:
This change has no impact on product appearance or solder-pad metallization, outer dimensions and footprint. The electro-optical performance remains the same. Appropriate electrical characterization and reliability qualification have been performed on the product to ensure normal parametric distribution, consistent electrical performance and reliability.

Effective Date of Change:
Product shipments using this change will begin after July-2026. Timing of shipment of the changed part will vary depending on customer demand and inventory levels.

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please acknowledge the receipt of the notice within 30 days of delivery. Lack of acknowledgement within 30 days constitutes acceptance of the change per JEDEC J-STD-046.